

CARRIER BASE MATERIAL

The antistatic epoxy glass laminate DC_261 material is able to resist extreme heat like lead free solder or flux chemicals. Due to its durability, this material is best used as printed circuit carriers or solder pallets.

- **Best material**
- **Heat resistant**
- **Long durability**



High heat resistant material for solder pallet

General description - Antistatic high-temperature and chemical resistant solder pallet material. DC_261 material which is highly stable at high temperature of lead free solder and flux chemicals.

Colour - Black

Application - Mostly used as PCB carrier or solder pallet in wave soldering process.

Sheet formats -2040x1200mm. Material also available as cut to size panels and machined parts.

Other dimensions on request. All thicknesses are stock items. Available thickness: 3, 4, 5, 6, 8, 10, 12, 14mm

Item	Unit	test condition	Actual value
Flexural strenght	Mpa	150 °C	235
Modulus of elasticity	Mpa	150 °C	19400
Coefficient of linear expansion	ppm/K	30 °C ~ 200 °C	9
Maximum operating temperature	°C		350
Standard operating temperature	°C		300
Flatness tolerance	mm		±0,15
Parallelism	mm		±0,08
Thickness tolerance	mm		±0,10
Water absorbtion	%		0,02
Thermal conductivity	W/mk		0,38

